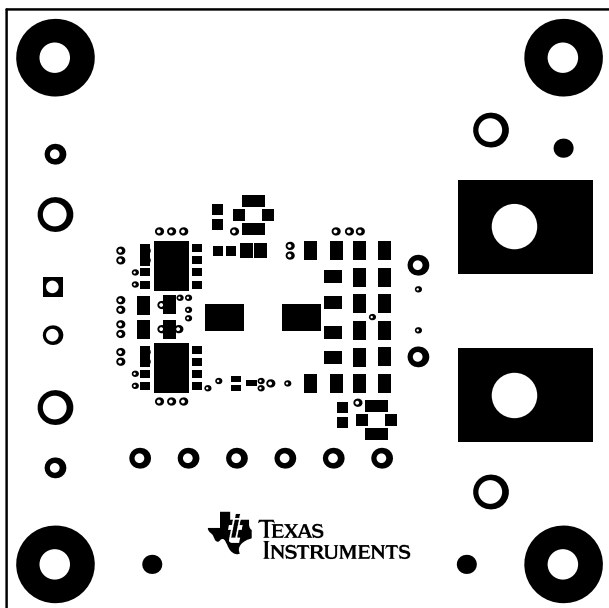
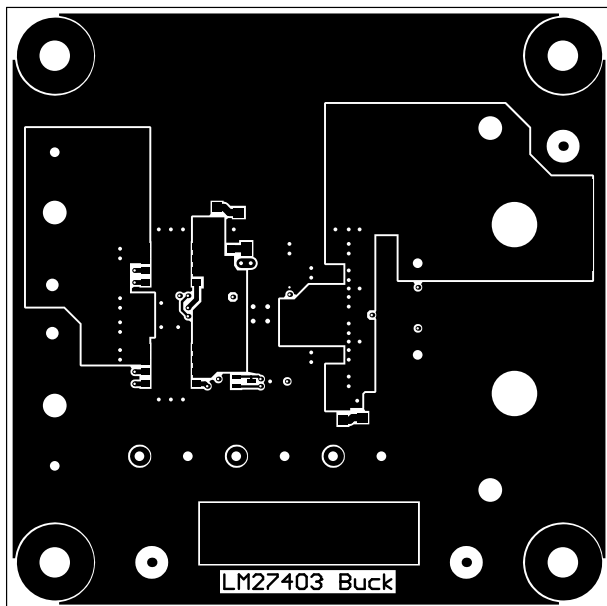


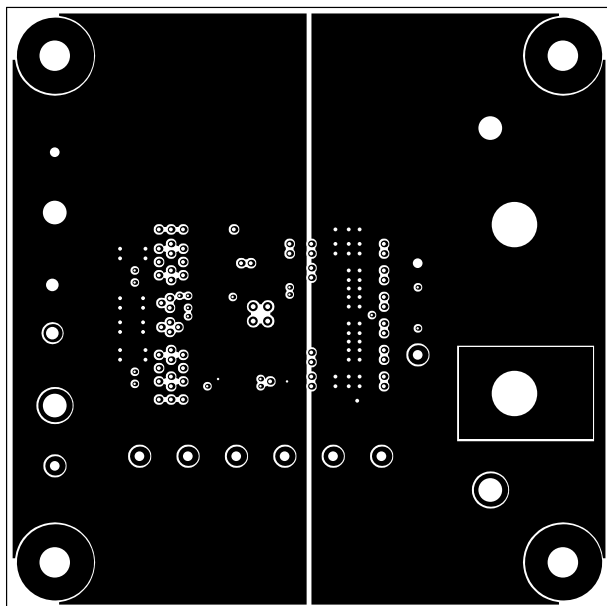
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7935	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 4/25/2013 1:06:32 PM	TEXAS INSTRUMENTS	



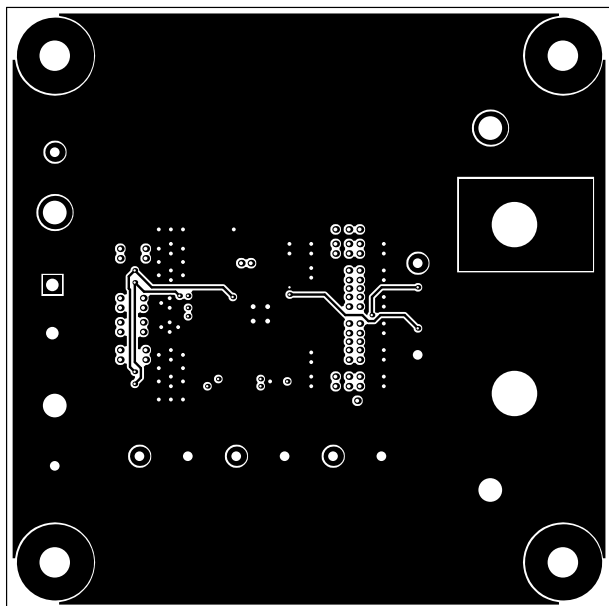
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7935	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 4/25/2013 1:06:33 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7935	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 4/25/2013 1:06:33 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7935	REV: B	SUN REV: Not In VersionControl
LAYER NAME = MidLayer1			
PLOT NAME = MidLayer1	GENERATED : 4/25/2013 1:06:34 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP7935

REV: B

SUN REV: Not In VersionControl

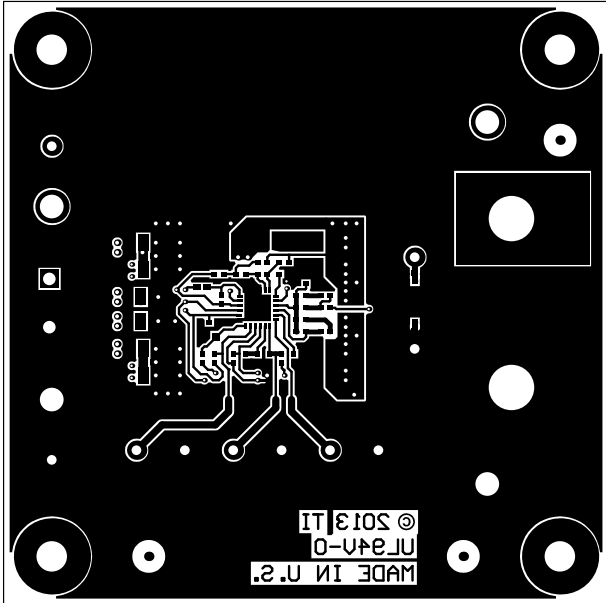
LAYER NAME = MidLayer2

PLOT NAME = MidLayer2

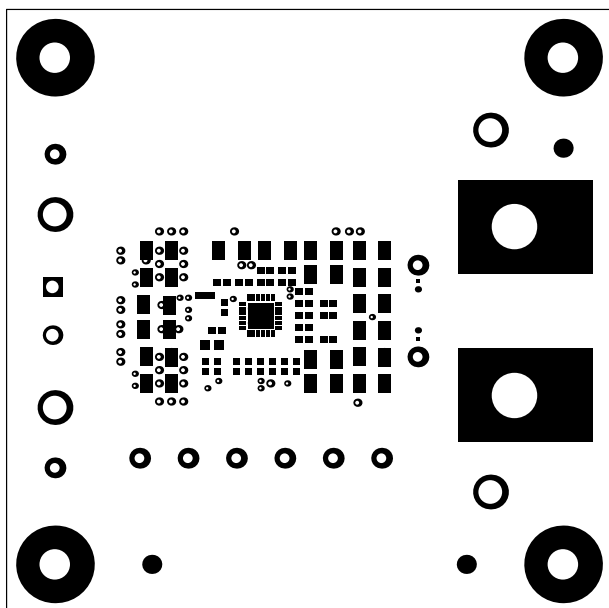
GENERATED : 4/25/2013 1:06:34 PM

TEXAS INSTRUMENTS

SUN Rev: Not In VersionControl



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7935	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 4/25/2013 1:06:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP7935

REV: B

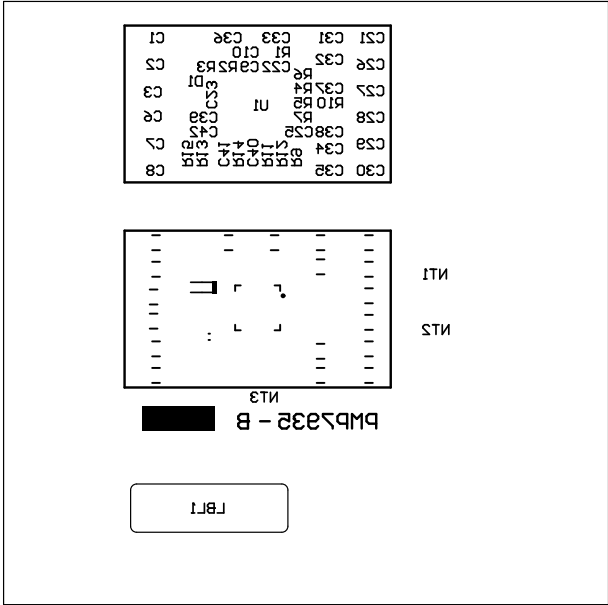
SUN REV: Not In VersionControl

LAYER NAME = Bottom Solder

PLOT NAME = Bottom Solder Mask

GENERATED : 4/25/2013 1:06:35 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP7935

REV: B

SUN REV: Not In VersionControl

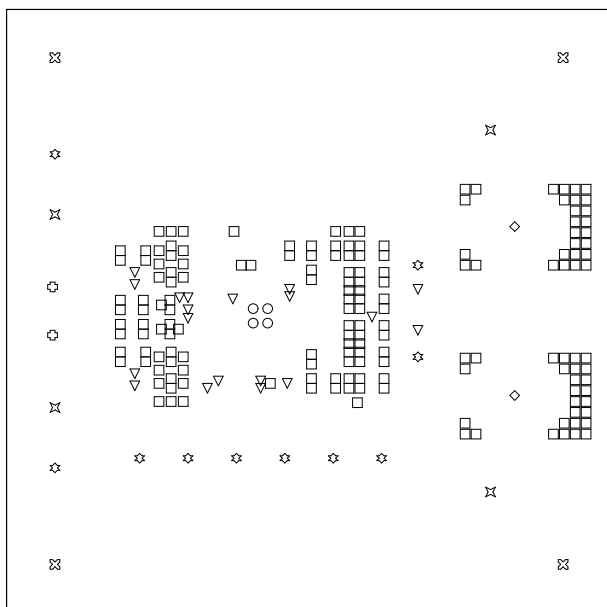
LAYER NAME = Bottom Overlay

PLOT NAME = Bottom Overlay

GENERATED : 4/25/2013 1:06:36 PM

TEXAS INSTRUMENTS

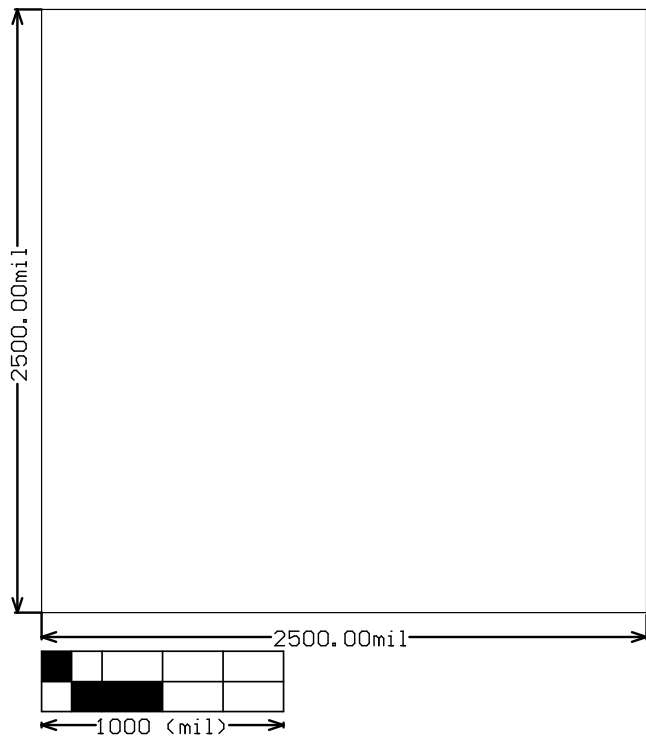




Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	19	10mil (0.254mm)	PTH	Round
□	167	16mil (0.406mm)	PTH	Round
○	4	20mil (0.508mm)	PTH	Round
☆	10	40mil (1.016mm)	PTH	Round
⊕	2	51.181mil (1.3mm)	PTH	Round
⊗	4	98.425mil (2.5mm)	PTH	Round
⊗	4	125.984mil (3.2mm)	PTH	Round
◇	2	188mil (4.775mm)	PTH	Round
	<b>212 Total</b>			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7935	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 4/25/2013 1:06:36 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7935	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 4/25/2013 1:06:37 PM	TEXAS INSTRUMENTS	

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